

## PRODUCT / PROCESS CHANGE NOTIFICATION

### 1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.		AMS/20/12142
1.3 Title of PCN		Introduction of new Resin, new Bonding wire and new DAP Plating on DPAK package in Subcontractor Nantong Fujitsu (TFME)
1.4 Product Category		See product list
1.5 Issue date		2020-08-11

### 2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Marcello SAN BIAGIO
2.1.2 Marketing Manager	Salvatore DI VINCENZO
2.1.3 Quality Manager	Giuseppe LISI

### 3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Bond wire material, diameter	Back end plant : Subcontractor Nantong Fujitsu (TFME China)

### 4. Description of change

	Old	New
4.1 Description	- Bonding wire : Gold 1.5 mil - Molding compound : EME-500HA, Sumitomo - Lead frame : TIN Plating Pure Sn with plating Ag die pad	- Bonding wire : CU 1.5 mil - Molding Compound: EME-G700HF, Sumitomo - Lead frame = TIN Plating Pure Sn with Bare Copper die pad and lock hole
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact	

### 5. Reason / motivation for change

5.1 Motivation	This change will contribute to ST's continuous service improvement and to improve the quality of the product, enhancing adhesion between lead frame surface & molding compound
5.2 Customer Benefit	QUALITY IMPROVEMENT

### 6. Marking of parts / traceability of change

6.1 Description	New finished good codes
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### 7. Timing / schedule

7.1 Date of qualification results	2020-04-30
7.2 Intended start of delivery	2020-10-10
7.3 Qualification sample available?	Upon Request

### 8. Qualification / Validation

8.1 Description	12142 12142_DPAK Cu wire.zip		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2020-08-11

**9. Attachments (additional documentations)**

12142 Public product.pdf  
12142\_12142\_DPAK Cu wire.zip

**10. Affected parts**

<b>10. 1 Current</b>		<b>10.2 New (if applicable)</b>
<b>10.1.1 Customer Part No</b>	<b>10.1.2 Supplier Part No</b>	<b>10.1.2 Supplier Part No</b>
L78M05ABDT-TR	L78M05ABDT-TR	
L78M05ACDT-TR	L78M05ACDT-TR	
L78M05CDT-TR	L78M05CDT-TR	
L78M09CDT-TR	L78M09CDT-TR	
L78M12CDT-TR	L78M12CDT-TR	
LD1117DT33CTR	LD1117DT33CTR	
LD1117DT33TR	LD1117DT33TR	
LD1117DT50TR	LD1117DT50TR	
LD1117DTTR	LD1117DTTR	

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## Public Products List

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**PCN Title :** Introduction of new Resin, new Bonding wire and new DAP Plating on DPAK package in Subcontractor Nantong Fujitsu (TFME)

**PCN Reference :** AMS/20/12142

**Subject :** Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

L78M05CDT-TR	LD1117DTTR	LD1117DT50TR
L78M12CDT-TR	LD1117DT33CTR	L78M05ABDT-TR
LD1117DT33TR	L78M05ACDT-TR	L78M09CDT-TR



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